

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|---------------------------------------------------------------------------------------------------------|----------------------------------------------------|-------------------|
| 30 | 38 | glass near (substrate or board) and (vias or (through near holes)) and filler and (display near device) | USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB | 2003/08/20 15: 56 |
| 31 | 52 | 361/760 and glass near (substrate or board) and (vias or (through near holes)) | USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB | 2003/08/20 15: 56 |
| 32 | 26 | 361/748 and glass near (substrate or board) and (vias or (through near holes)) | USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB | 2003/08/20 15: 57 |
| 33 | 15 | 361/750 and glass near (substrate or board) and (vias or (through near holes)) | USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB | 2003/08/20 15: 57 |
| 34 | 13 | 361/751 and glass near (substrate or board) and (vias or (through near holes)) | USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB | 2003/08/20 15: 57 |
| 35 | 16 | 361/761 and glass near (substrate or board) and (vias or (through near holes)) | USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB | 2003/08/20 15: 57 |
| 36 | 8 | 361/765 and glass near (substrate or board) and (vias or (through near holes)) | USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB | 2003/08/20 15: 57 |
| 37 | 19 | 361/767 and glass near (substrate or board) and (vias or (through near holes)) | USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB | 2003/08/20 15: 57 |
| 38 | 7 | 361/768 and glass near (substrate or board) and (vias or (through near holes)) | USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB | 2003/08/20 15: 57 |
| 39 | 10 | 361/772 and glass near (substrate or board) and (vias or (through near holes)) | USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB | 2003/08/20 15: 57 |
| 40 | 0 | roehling.in. and eves.in. and hewlett.as. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/08/20 15: 57 |
| 41 | 1 | roehling.in. and eves.in. | EPO; JPO; DERWENT | 2003/08/20 15: 57 |